Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

1 (previously presented): A chip-packaging with bonding options having a plurality of package substrates, comprising:

a first package substrate having a high voltage or a low voltage;

a second package substrate having a high voltage or a low voltage, the voltage level of the first package substrate being the logical opposite of the voltage level of the second package substrate; and

a chip mounted on first package substrate, the chip comprising a plurality of bonding option pads,

wherein each bonding option pad of the chip is selectively connected to the first package substrate or the second package substrate.

2 (cancelled).

3 (previously presented): The chip-packaging of the claim 1 wherein the high voltage is the voltage of the power supply and the low voltage is the ground voltage.

4 (currently amended): The chip-packaging of the claim 1 further comprising a plurality of leads ~~lead frames~~, wherein each lead ~~frame~~ is connected to one pin of the chip-packaging.

5 (original): The chip-packaging of the claim 4 wherein the pin is connected to a high voltage, a low voltage, or an input/output signal.

6 (cancelled).

7 (original): The chip-packaging of the claim 1 wherein the first package substrate extends outside the chip and the second package substrate surrounds the chip.

8 (previously presented): The chip-packaging of the claim 1 wherein the first package substrate and the second package substrate substantially approximate each of a plurality of the bonding pads.

9-18 (cancelled).

19 (previously presented): The chip-packaging of the claim 4 wherein the pin is connected to an input/output signal.

20 (currently amended): The chip-packaging of the claim 1 further comprising a plurality of leads ~~lead frames~~, each bonding option pad of the chip having a corresponding lead ~~frame~~, wherein each bonding option pad is selectively connected to the first package substrate, the second package substrate, or the corresponding lead ~~frame~~.